

**HSEC8-DV SERIES**

**(0,80 mm) .0315"**

# VERTICAL EDGE RATE® CARD SOCKET

**SPECIFICATIONS**

For complete specifications and recommended PCB layouts see [www.samtec.com?HSEC8-DV](http://www.samtec.com?HSEC8-DV)

**Insulator Material:** Black Liquid Crystal Polymer  
**Contact:** BeCu  
**Plating:** Au or Sn over 50µ" (1,27 µm) Ni  
**Current Rating:** 2.8 A per pin (2 adjacent pins powered)  
**Operating Temp:** -55°C to +125°C  
**Card Insertion Depth:** (3,15 mm) .125" nominal  
**RoHS Compliant:** Yes

**Processing:**

**Lead-Free Solderable:** Yes  
**SMT Lead Coplanarity:** (0,10 mm) .004" max (10-60)

**RECOGNITIONS**

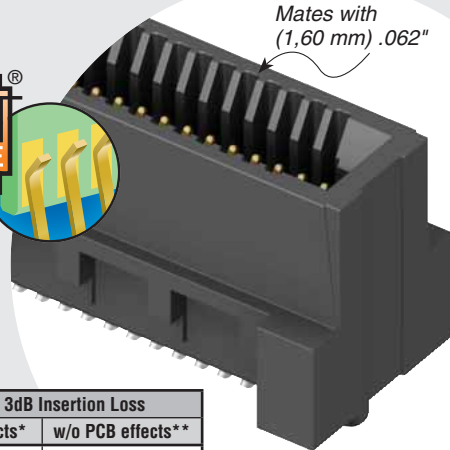
For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



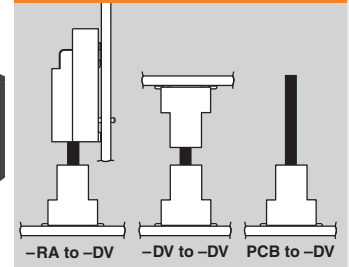
**Mates with:**  
 1,60 mm thick cards,  
 ECDP, HSC8



**HIGH SPEED CABLE APPLICATIONS**



**BOARD-TO-BOARD APPLICATIONS**



HSEC8	Rated @ 3dB Insertion Loss	
	with PCB effects*	w/o PCB effects**
7,98 mm Stack Height		
Single-Ended Signaling	8 GHz / 16 Gbps	17 GHz / 34 Gbps
Differential Pair Signaling	10.5 GHz / 21 Gbps	15.5 GHz / 31 Gbps

\*Performance data includes effects of a non-optimized PCB.  
 \*\*Test board losses de-embedded from performance data.  
 Complete test data available at [www.samtec.com?HSEC8-DV](http://www.samtec.com?HSEC8-DV) or contact [sig@samtec.com](mailto:sig@samtec.com)



**HSEC8** - **1** POSITIONS PER ROW - **CARD THICKNESS** - **PLATING OPTION** - **DV** - **A** - **OTHER OPTION**

**09, 10, 13, 20, 25, 30, 37, 40, 49, 50, 60, 70, 80, 100**  
 (13, 25, 49 only available with -L or -L2 option;  
 09 only available with -L2 option;  
 37 only available with -L option)

**-01**  
 = (1,60 mm) .062" thick card  
**-03**  
 = (2,36 mm) .093" thick card

CABLE	CONNECTOR
ECDP-04	HSEC8-109-L2
ECDP-08	HSEC8-113-L2
ECDP-16	HSEC8-125-L2
ECDP-32	HSEC8-149-L2

**-L**  
 = 10µ" (0,25 µm) Gold on contact, Matte Tin on tail  
**-S**  
 = 30µ" (0,76 µm) Gold on contact, Matte Tin on tail

**-K**  
 = (7,01 mm) .276" DIA Polyimide Film Pick & Place Pad (with -01 card)  
 = (6,25 mm) .246" DIA Polyimide Film Pick & Place Pad (with -03 card)

**-BL**  
 = Board Locks (40, 50, 60, 80 only) (Other sizes available. Contact Samtec.)

**-L**  
 = Latching Option (13, 25, 37, 49 only) (For use with EEDP)

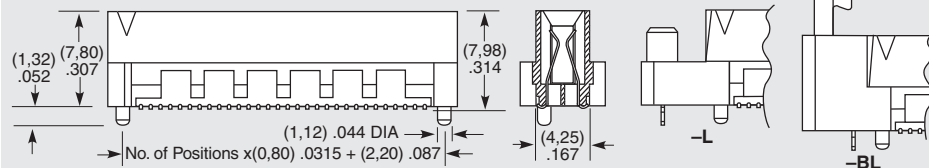
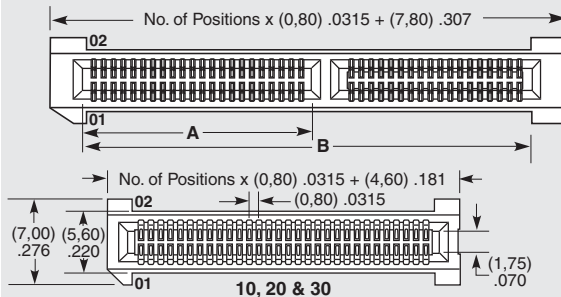
**-L2**  
 = ECDP Latching (09, 13, 25, 49 only) (For use with ECDP)

**-WT**  
 = Weld tab

**-TR**  
 = Tape & Reel (09 - 70 only)

POSITIONS PER ROW	A	B
09†	(4,50) .177	(11,80) .465
13†	(6,10) .240	(15,00) .591
25†	(6,10) .240	(24,60) .969
37†	(18,10) .713	(34,20) 1.346
40	(18,90) .744	(36,60) 1.441
49†	(22,90) .902	(43,80) 1.724
50	(22,90) .902	(44,60) 1.756
60	(26,90) 1.059	(52,60) 2.071
70†	(26,90) 1.059	(60,60) 2.386
80†	(26,90) 1.059	(68,60) 2.701
100†	(26,90) 1.059	(84,60) 3.331

Positions where no dimensions are given do not have keying feature.  
 \* Mates with ECDP Series.  
 † Available with -01 Card Only.



**Note:** While optimized for 50Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75Ω applications. Contact Samtec for further information.  
**Note:** Some lengths, styles and options are non-standard, non-returnable.